

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	FBAR and piezoelectric and duplexer and (FBAR adj chip) and air and gap	USPAT	OR	ON	2005/03/08 17:27
L2	0	FBAR and piezoelectric and duplexer and (FBAR adj chip)	USPAT	OR	ON	2005/03/08 17:28
L3	9	FBAR and piezoelectric and duplexer and transmitter and receiver	USPAT	OR	ON	2005/03/08 17:43
L4	607	438/26	USPAT	OR	ON	2005/03/08 17:43
L5	570	438/51	USPAT	OR	ON	2005/03/08 17:43
L6	327	438/55	USPAT	OR	ON	2005/03/08 17:44
L7	521	438/64	USPAT	OR	ON	2005/03/08 17:44
L8	2912	438/106	USPAT	OR	ON	2005/03/08 17:44
L9	1705	438/107	USPAT	OR	ON	2005/03/08 17:44
L10	2062	438/108	USPAT	OR	ON	2005/03/08 17:44
L11	1016	438/112	USPAT	OR	ON	2005/03/08 17:44
L12	2085	438/118	USPAT	OR	ON	2005/03/08 17:44
L13	698	438/119	USPAT	OR	ON	2005/03/08 17:44
L14	921	438/122	USPAT	OR	ON	2005/03/08 17:44
L15	1226	438/124	USPAT	OR	ON	2005/03/08 17:44
L16	1264	438/126	USPAT	OR	ON	2005/03/08 17:44
L17	1665	438/127	USPAT	OR	ON	2005/03/08 17:45
S25	1	("6407649").PN.	USPAT	OR	OFF	2005/03/08 15:33
S26	0	S17 and (FBAR or chip or air or gap or piezoelectric or arrange or duplexer or bump or ball or surface or ratio or protective or plurlity or reversing or bonding or side or structure or electrical or duplexing or molding or substrate or sacrificial or electrically or dry or removing or PCB or solution or physical or process or simultaneously or chemical or high or pressure or dispensing)	USPAT	OR	ON	2005/03/08 15:38

S27	1	S25 and (FBAR or chip or air or gap or piezoelectric or arrange or duplexer or bump or ball or surface or ratio or protective or plurlity or reversing or bonding or side or structure or electrical or duplexing or molding or substrate or sacrificial or electrically or dry or removing or PCB or solution or physical or process or simultaneously or chemical or high or pressure or dispensing)	USPAT	OR	ON	2005/03/08 15:55
S28	1	"6339276".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:42
S29	1	"6307447".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:43
S30	1	"6262637".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:43
S31	1	"6107721".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:44
S32	1	"6060818".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:45
S33	1	"5910756".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:45
S34	1	"5894647".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:45
S35	1	"5873154".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:45
S36	1	"5714917".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:45
S37	1	"5587620".PN.	USPAT; USOCR	OR	ON	2005/03/08 15:45
S38	0	FBAR and piezoelectric and duplexer and (duplexer adj substrate) and (air adj gap) and chip and electrode and pad and bump and ball	USPAT	OR	ON	2005/03/08 15:48
S39	0	FBAR and piezoelectric and duplexer and (duplexer adj substrate) and chip and electrode and pad and bump and ball	USPAT	OR	ON	2005/03/08 15:55
S40	2	FBAR and piezoelectric and duplexer and chip and electrode and pad and bump and ball	USPAT	OR	ON	2005/03/08 17:26

S41	2	S40 and (FBAR or chip or air or gap or piezoelectric or arrange or duplexer or bump or ball or surface or ratio or protective or plurlity or reversing or bonding or side or structure or electrical or duplexing or molding or substrate or sacrificial or electrically or dry or removing or PCB or solution or physical or process or simultaneously or chemical or high or pressure or dispensing)	USPAT	OR	ON	2005/03/08 15:55
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